

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) A method of distributing power in a semiconductor die, comprising;

providing at least one pair of bond pads to the semiconductor die;

providing an input/output bond pad to an outer periphery of the semiconductor die, the input/output bond pad to receive an input/output bond wire operable for electrically connecting to a lead finger of a package, wherein the lead finger is arranged on the package outside of the outer periphery of the semiconductor die;

connecting a single corresponding bond wire between each of the at least one pair of bond pads such that each bond pad of each of the at least one pair of bond pads has only one bond wire end connected thereto;~~and~~

locating a first bond pad of the at least one pair of bond pads in an internal portion of the semiconductor die; and

electrically connecting the input/output bond pad to a second bond pad of the at least one pair of bond pads.

2. (Currently Amended) The method of Claim 1 further comprising locating a the second bond pad of the at least one pair of bond pads along a periphery of the semiconductor die.

3. (Previously Presented) The method of Claim 1 wherein the single corresponding bond wire comprises a metallic material selected from the group consisting of gold, aluminum, and copper.

4. (Previously Presented) The method of Claim 1 further comprising bonding the single corresponding bond wire to the pair of bond pads using a wire bond type selected from the group consisting of ball bonds, stitch bonds, stitch bonds on bonding pad, and stitch bonds on ball.

5. (Previously Presented) The method of Claim 1 further comprising connecting a trace in the semiconductor die between bond pads of the pair of bond pads.

6. (Previously Presented) The method of Claim 1 further comprising locating a second bond pad of the at least one pair of bond pads in the internal portion of the semiconductor die.

7. (Previously Presented) The method of Claim 1 wherein the single corresponding bond wire is selected from the group consisting of power interconnects, ground interconnects, and signal interconnects.

8. (Previously Presented) The method of Claim 1 further comprising:
attaching a plurality of pairs of bond pads to the semiconductor die; and
connecting a corresponding wire between each of the pairs of bond pads
such that each bond pad of the pairs of bond pads includes a single wire bond.

9. (Previously Presented) The method of Claim 1 further comprising locating
the input/output bond pad on a first bond surface and a second bond pad of the at least
one pair of bond pads on the first bond surface.

10. (New) A method of distributing power in a semiconductor die, comprising;
providing an input/output bond pad to an outer periphery of the
semiconductor die;
electrically connecting an input/output bond wire from a lead finger that is
arranged on a package and that is located outside of the outer periphery of the
semiconductor die to the input/output bond pad;
providing first and second of bond pads to the semiconductor die;
connecting a first bond wire between the first and second bond pads; and
connecting the input/output bond pad to the first bond pad using at least
one of a trace and a common bonding surface,
wherein the first and second bond pads and the input/output bond pad
have only one bond wire end connected thereto.

11. (New) The method of Claim 10 further comprising locating the first bond pad in the outer periphery of the semiconductor die.

12. (New) The method of Claim 11 further comprising locating the second bond pad in the outer periphery of the semiconductor die.

13. (New) The method of Claim 11 further comprising locating the second bond pad in an inner portion of the semiconductor die.

14. (New) The method of Claim 10 wherein the first bond wire comprises a metallic material selected from the group consisting of gold, aluminum, and copper.

15. (New) The method of Claim 10 further comprising bonding the first bond wire to the first and second bond pads using a wire bond type selected from the group consisting of ball bonds, stitch bonds, stitch bonds on bonding pad, and stitch bonds on ball.

16. (New) The method of Claim 10 wherein the first bond wire is selected from the group consisting of power interconnects, ground interconnects, and signal interconnects.

17. (New) The method of Claim 10 further comprising:
attaching a plurality of pairs of bond pads to the semiconductor die; and
connecting a corresponding wire between each of the pairs of bond pads
such that each bond pad of the pairs of bond pads includes a single wire bond.

18. (New) The method of Claim 10 further comprising locating the
input/output bond pad on a first bond surface and a second bond pad of the at least one
pair of bond pads on the first bond surface.